



US 20240179850A1

(19) **United States**

(12) **Patent Application Publication**  
**JUNG et al.**

(10) **Pub. No.: US 2024/0179850 A1**

(43) **Pub. Date: May 30, 2024**

(54) **ELECTRONIC DEVICE AND  
MANUFACTURING METHOD THEREFOR**

(30) **Foreign Application Priority Data**

Aug. 5, 2021 (KR) ..... 10-2021-0103137

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**Publication Classification**

(51) **Int. Cl.**

**H05K 3/34** (2006.01)

**B23K 1/002** (2006.01)

**B23K 101/42** (2006.01)

**H05K 3/10** (2006.01)

**H05K 3/42** (2006.01)

(52) **U.S. Cl.**

CPC ..... **H05K 3/3485** (2020.08); **B23K 1/002**

(2013.01); **H05K 3/101** (2013.01); **H05K**

**3/3494** (2013.01); **H05K 3/429** (2013.01);

**B23K 2101/42** (2018.08); **H05K 2203/0126**

(2013.01); **H05K 2203/101** (2013.01)

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(21) Appl. No.: **18/432,807**

(57) **ABSTRACT**

An electronic device includes an injection mold including a mounting part and a wiring groove, a plated wiring plated on the wiring groove, and an electronic element mounted on the mounting part and electrically connected to the plated wiring, wherein the plated wiring is plated on an outer region of the injection mold, and the electronic element mounted on the injection mold dispensed on the plated wiring.

(22) Filed: **Feb. 5, 2024**

**Related U.S. Application Data**

(63) Continuation of application No. PCT/KR22/11198,  
filed on Jul. 29, 2022.

